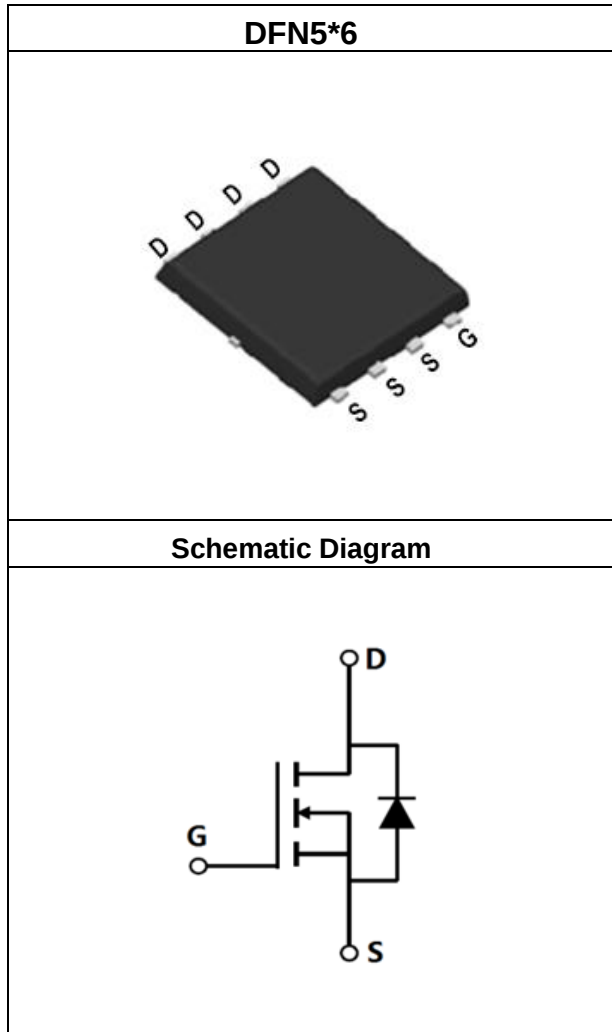


N-channel 40V, 2.3mΩ typ.,
SGT MOSFET S2 in DFN5*6

Datasheet - production data

1. Descriptions



Key Performance Parameters

Parameters	Value	Unit
BV_{DSS}	40	V
$R_{DS(on),max}$	2.6	mΩ
$Q_{g,typ}$	42	nC
$I_{D,pulse}$	380	A
E_{AS}	342	mJ

Features

- Extremely Low Losses Due to Very Low FOM $R_{ds(on)} \cdot Q_g$.
- High-Speed Switching.
- Qualified for Industrial Grade Applications According to JEDEC.
- 100% UIS Tested.

Applications

High-Efficiency DC-DC Converters, High-Frequency Switching and Synchronous Rectification, Motor Drivers.

Type/Ordering Code	Package	Marking	Related Links
CSLS024N04S2	DFN5*6	024N04S2	see Appendix A

Contents

1.	Descriptions	1
2.	Maximum Ratings.....	3
3.	Thermal Characteristics	4
4.	Electrical Characteristics	5
5.	Electrical Characteristics Diagrams	6
6.	Test Circuits	10
7.	Package Outlines	11
8.	Appendix.....	12

2. Maximum Ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 1. Absolute Maximum Ratings

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
V_{DS}	Drain-Source Voltage ¹⁾	-	-	40	V	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$
I_D	Continuous Drain Current (Silicon Limited)	-	-	110	A	$T_C=25^\circ\text{C}$
$I_{D,pulse}$	Pulsed Drain Current	-	-	380	A	$T_C=25^\circ\text{C}$
E_{AS}	Avalanche Energy, Single Pulse ²⁾	-	-	342	mJ	$I_D=37\text{A}$; $V_{DD}=50\text{V}$
I_{AS}	Avalanche Current	-	-	37	A	-
V_{GS}	Gate Source Voltage	-20	-	20	V	Static; AC ($f > 1\text{ Hz}$)
P_{tot}	Power Dissipation	-	-	83	W	$T_C=25^\circ\text{C}$
T_J, T_{stg}	Operating and Storage Temperature	-55	-	150	$^\circ\text{C}$	-
I_S	Continuous Diode Forward Current	-	-	110	A	$T_C=25^\circ\text{C}$
$I_{S,pulse}$	Diode Pulse Current ²⁾	-	-	380	A	$T_C=25^\circ\text{C}$

1) Limited by T_j max. Maximum Duty Cycle $D=0.75$.

2) $V_{DD}=50\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$, Starting $T_j=25^\circ\text{C}$.

3. Thermal Characteristics

Table 2. Thermal Characteristics

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
R_{thJC}	Thermal Resistance, Junction - Case	-	-	1.5	°C/W	$T_C=25^{\circ}\text{C}$
R_{thJA}	Thermal Resistance, Junction - Ambient	-	-	65	°C/W	$T_C=25^{\circ}\text{C}$
T_{sold}	Soldering Temperature, Wavesoldering Only Allowed at Leads	-	-	260	°C	Lead Temperature (Soldering, 10 sec)

4. Electrical Characteristics

at $T_J = 25^\circ\text{C}$, unless otherwise specified

Table 3. Static Characteristics

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	40	-	-	V	$V_{GS}=0V, I_D=250\mu A$
$V_{(GS)th}$	Gate Threshold Voltage	1.0	1.8	2.5	V	$V_{DS}=V_{GS}, I_D=250\mu A$
I_{DSS}	Zero Gate Voltage Drain Current	-	-	1	μA	$V_{DS}=40V, V_{GS}=0V, T_J=25^\circ C$
I_{GSS}	Gate-Source Leakage Current	-	-	± 100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
$R_{DS(on)}$	Drain-Source On-State Resistance	-	2.3	2.6	m Ω	$V_{GS}=10V, I_D=20A, T_J=25^\circ C$
R_G	Gate resistance	-	3	-	Ω	$V_{DD}=0V, V_{GS}=0V, F=1MHz$
g_{fs}	Transconductance		120		S	$V_{DS}=5V, I_D=20A$

Table 4. Dynamic Characteristics

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
C_{iss}	Input Capacitance	-	2920	-	pF	$V_{GS}=0V, V_{DS}=20V, f=250kHz$
C_{oss}	Output Capacitance	-	727	-	pF	$V_{GS}=0V, V_{DS}=20V, f=250kHz$
C_{rss}	Reverse Transfer Capacitance	-	55	-	pF	$V_{GS}=0V, V_{DS}=20V, f=250kHz$
$t_{d(on)}$	Turn-On Delay Time	-	19	-	ns	$V_{DD}=20V, V_{GS}=10V, I_D=20A, R_G=7.5\Omega$
t_r	Rise Time	-	45	-	ns	$V_{DD}=20V, V_{GS}=10V, I_D=20A, R_G=7.5\Omega$
$t_{d(off)}$	Turn-Off Delay Time	-	63	-	ns	$V_{DD}=20V, V_{GS}=10V, I_D=20A, R_G=7.5\Omega$
t_f	Fall Time	-	18	-	ns	$V_{DD}=20V, V_{GS}=10V, I_D=20A, R_G=7.5\Omega$

Table 5. Gate Charge Characteristics

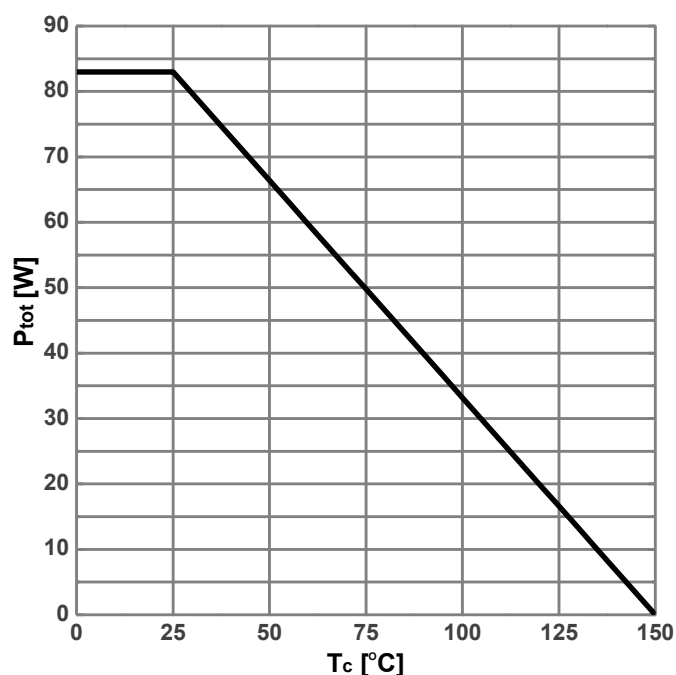
Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Q_{gs}	Gate to Source Charge	-	5.4	-	nC	$V_{DD}=20V, I_D=20A, V_{GS}=0 \text{ to } 10V$
Q_{gd}	Gate to Drain Charge	-	4.3	-	nC	$V_{DD}=20V, I_D=20A, V_{GS}=0 \text{ to } 10V$
Q_g	Gate Charge Total	-	42	-	nC	$V_{DD}=20V, I_D=20A, V_{GS}=0 \text{ to } 10V$
$V_{plateau}$	Gate Plateau Voltage	-	2	-	V	$V_{DD}=20V, I_D=20A, V_{GS}=0 \text{ to } 10V$

Table 6. Reverse Diode Characteristics

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
V_{SD}	Diode Forward Voltage	-	0.8	-	V	$V_{GS}=0V, I_F=20A, T_J=25^\circ C$
t_{rr}	Reverse Recovery Time	-	42	-	ns	$V_R=20V, I_F=20A, dI_F/dt=100A/\mu s$
Q_{rr}	Reverse Recovery Charge	-	45	-	nC	$V_R=20V, I_F=20A, dI_F/dt=100A/\mu s$

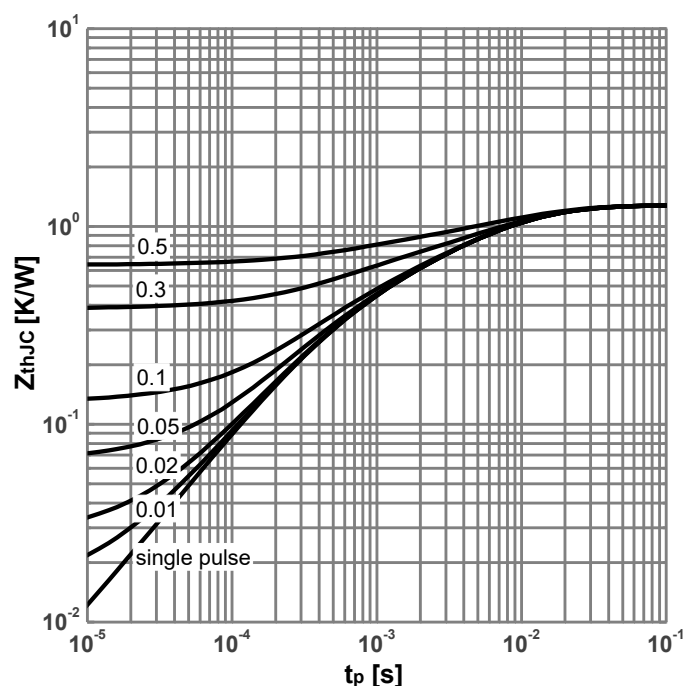
5. Electrical Characteristics Diagrams

Diagram 1: Power Dissipation



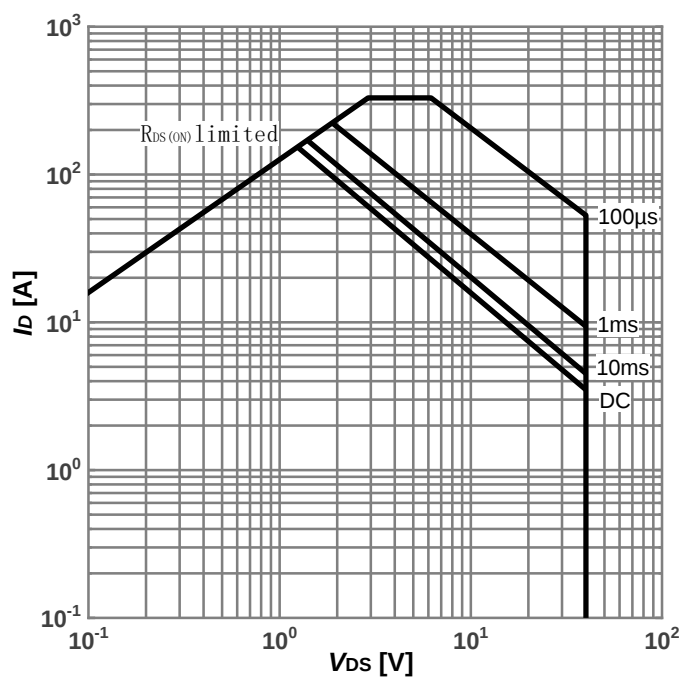
$$P_{tot}=f(T_c)$$

Diagram 2: Max. Transient Thermal Impedance



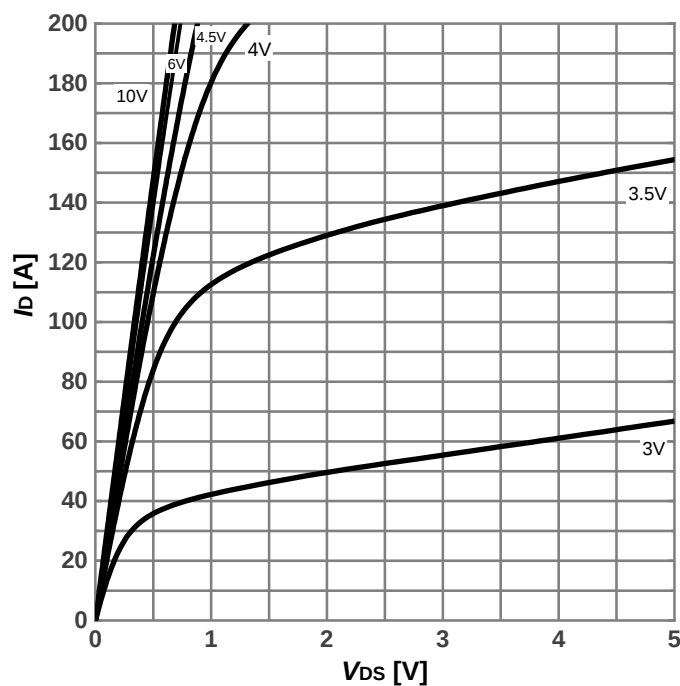
$$Z_{thJC}=f(t_p); \text{ parameter: } D=t_p/T$$

Diagram 3: Safe Operating Area



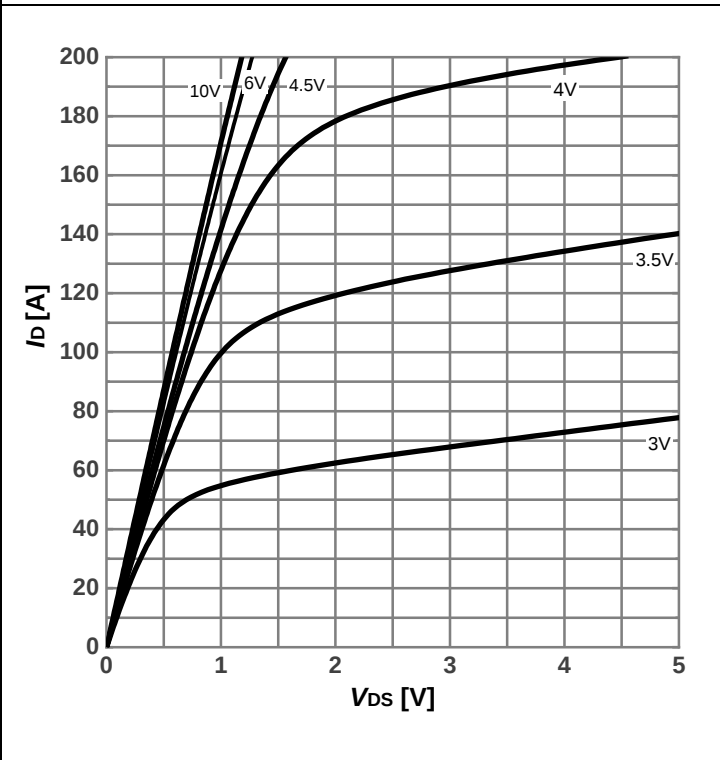
$$I_D=f(V_{DS}); T_J=25^{\circ}\text{C}; D=0; \text{ parameter: } t_p$$

Diagram 4: Typ. Output Characteristics



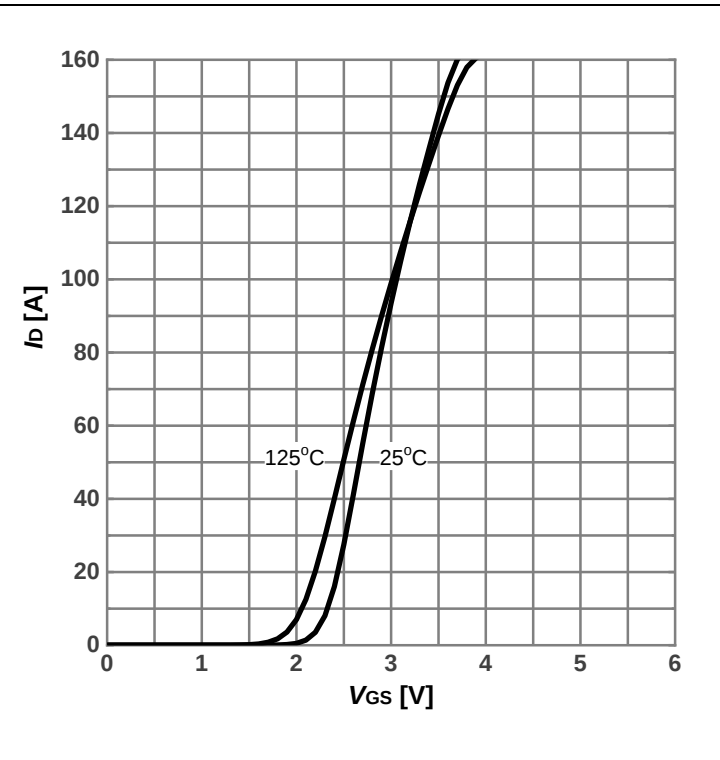
$$I_D=f(V_{DS}); T_J=25^{\circ}\text{C}; \text{ parameter: } V_{GS}$$

Diagram 5: Typ. Output Characteristics



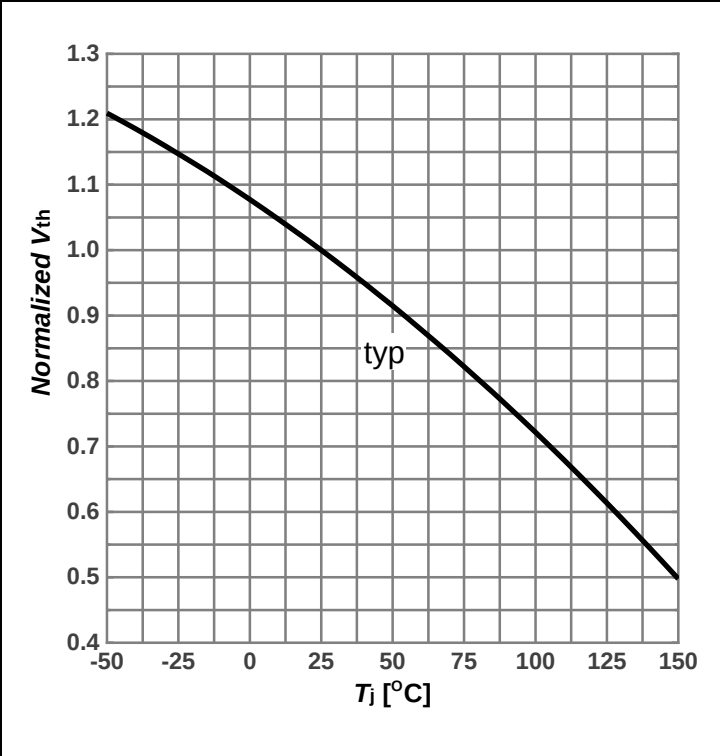
$I_D=f(V_{DS})$; $T_J=125^{\circ}\text{C}$; parameter: V_{GS}

Diagram 6: Typ. Transfer Characteristics



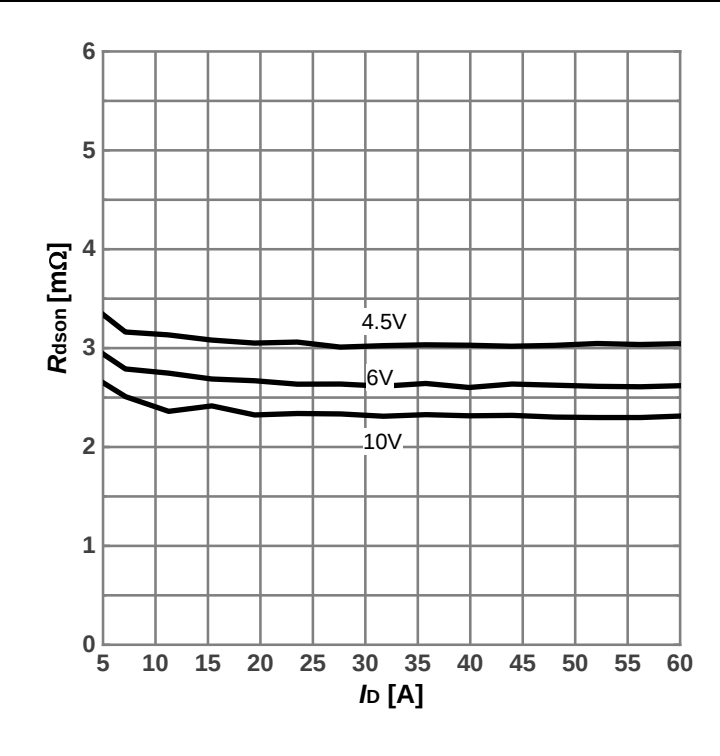
$I_D=f(V_{GS})$; $V_{DS}=15\text{V}$; parameter: T_J

Diagram 7: Gate Threshold Voltage vs. Junction Temperature

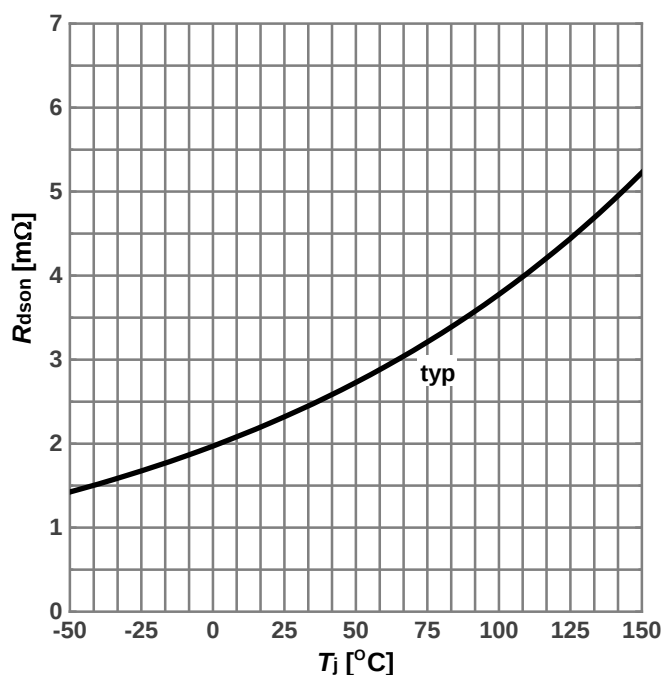


$V_{th}=f(T_J)$; $I_D=250\mu\text{A}$

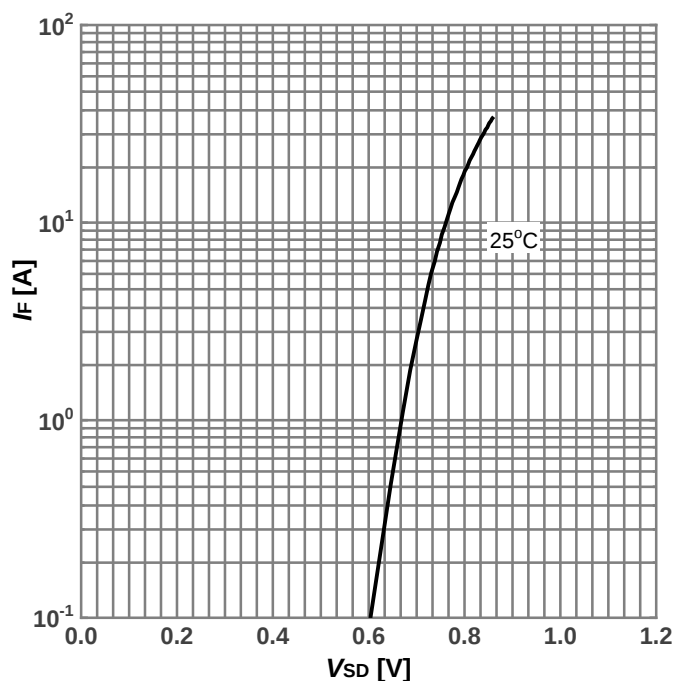
Diagram 8: On-State Resistance vs. Drain Current



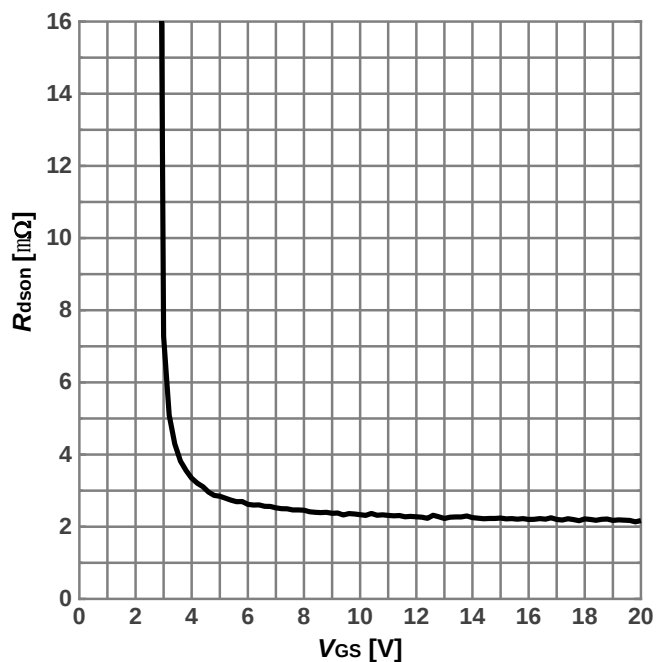
$R_{DS(on)}=f(I_D)$; $T_J=25^{\circ}\text{C}$; parameter: V_{GS}

Diagram 9: On-State Resistance vs. Junction Temperature

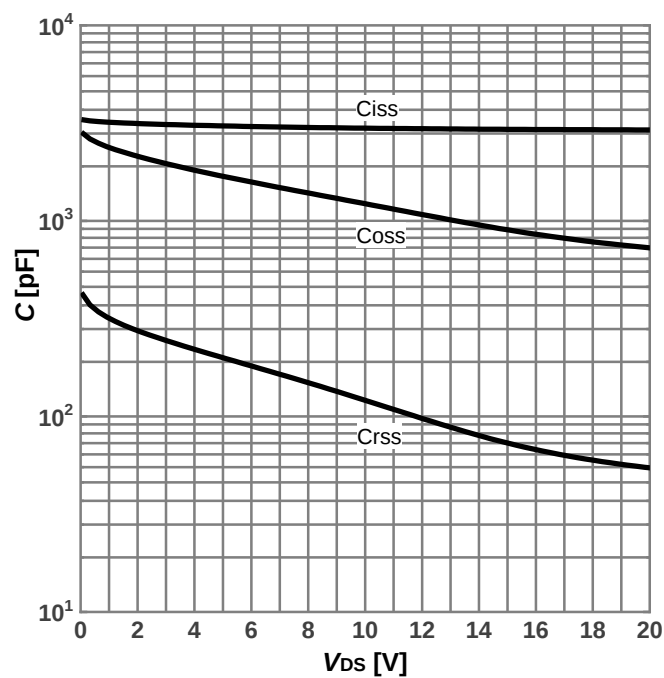
$$R_{DS(on)} = f(T_J); I_D = 20A; V_{GS} = 10V$$

Diagram 10: Forward Characteristics of Reverse Diode

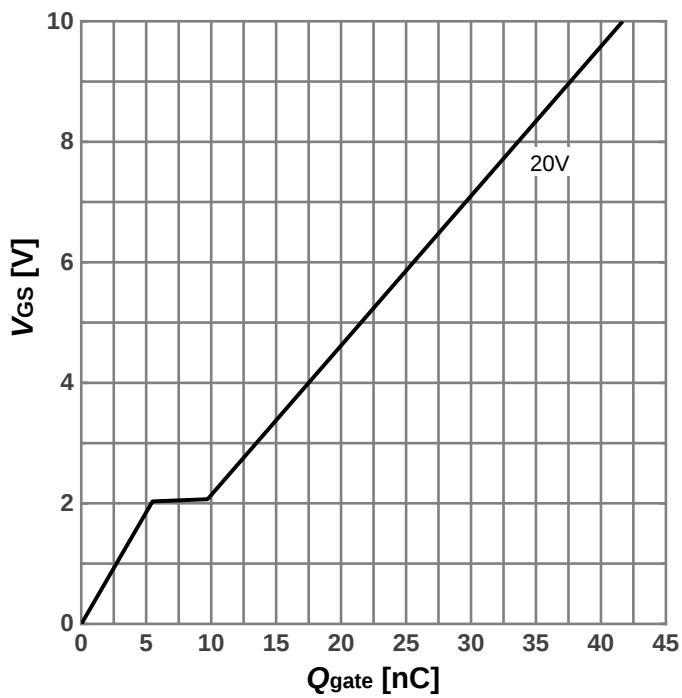
$$I_F = f(V_{SD}); \text{parameter: } T_J$$

Diagram 11: On-State Resistance vs. Vgs Characteristics

$$R_{DS(on)} = f(V_{GS}); T_J = 25^\circ C; I_D = 20A$$

Diagram 12: Typ. Capacitances

$$C = f(V_{DS}); V_{GS} = 0V; f = 250kHz$$

Diagram 13: Typ. Gate Charge

$V_{GS}=f(Q_{gate})$; $I_D=20A$ pulsed; $V_{DS}=20V$

6. Test Circuits

Table 7. Diode Characteristics

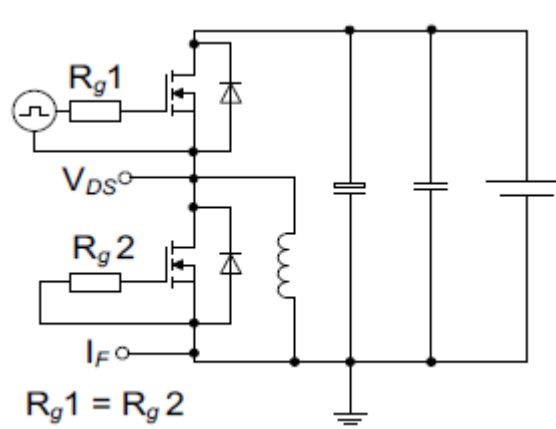
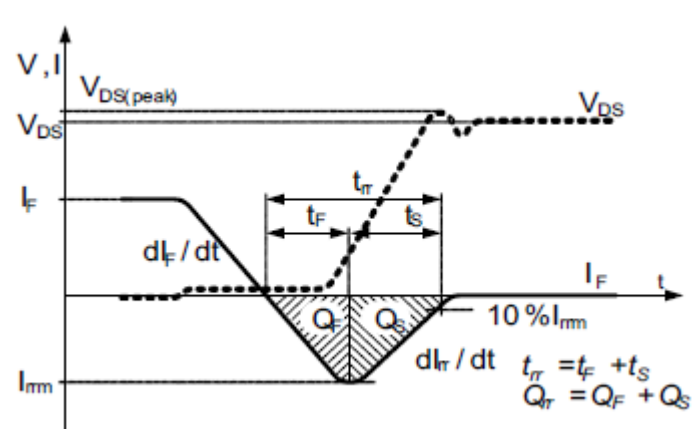
Test Circuit for Diode Characteristics	Diode Recovery Waveform
 $R_{g1} = R_{g2}$	 $V_{DS(peak)}$ V_{DS} I_F dI_F/dt t_F t_S t_{rr} I_{rm} $10\% I_{rm}$ dI_{rr}/dt $t_{rr} = t_F + t_S$ $Q_{rr} = Q_F + Q_S$

Table 8. Switching Times

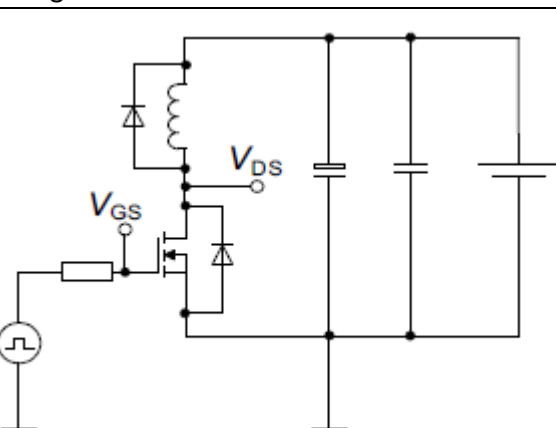
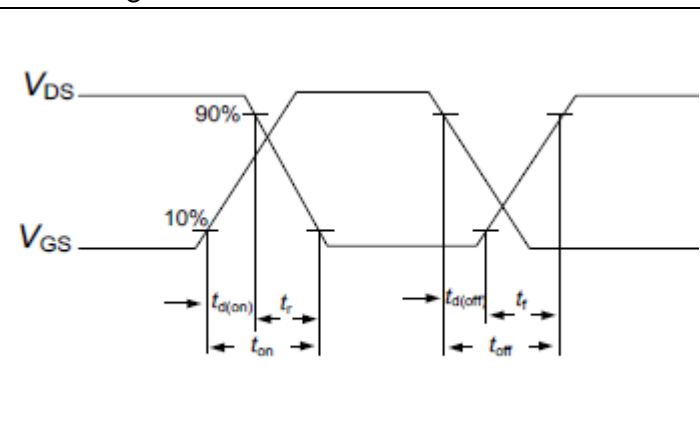
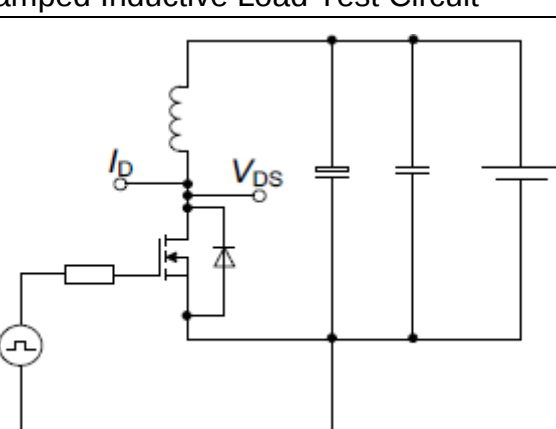
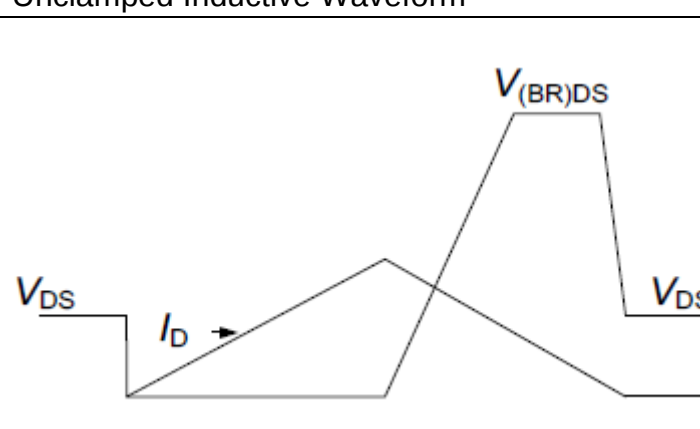
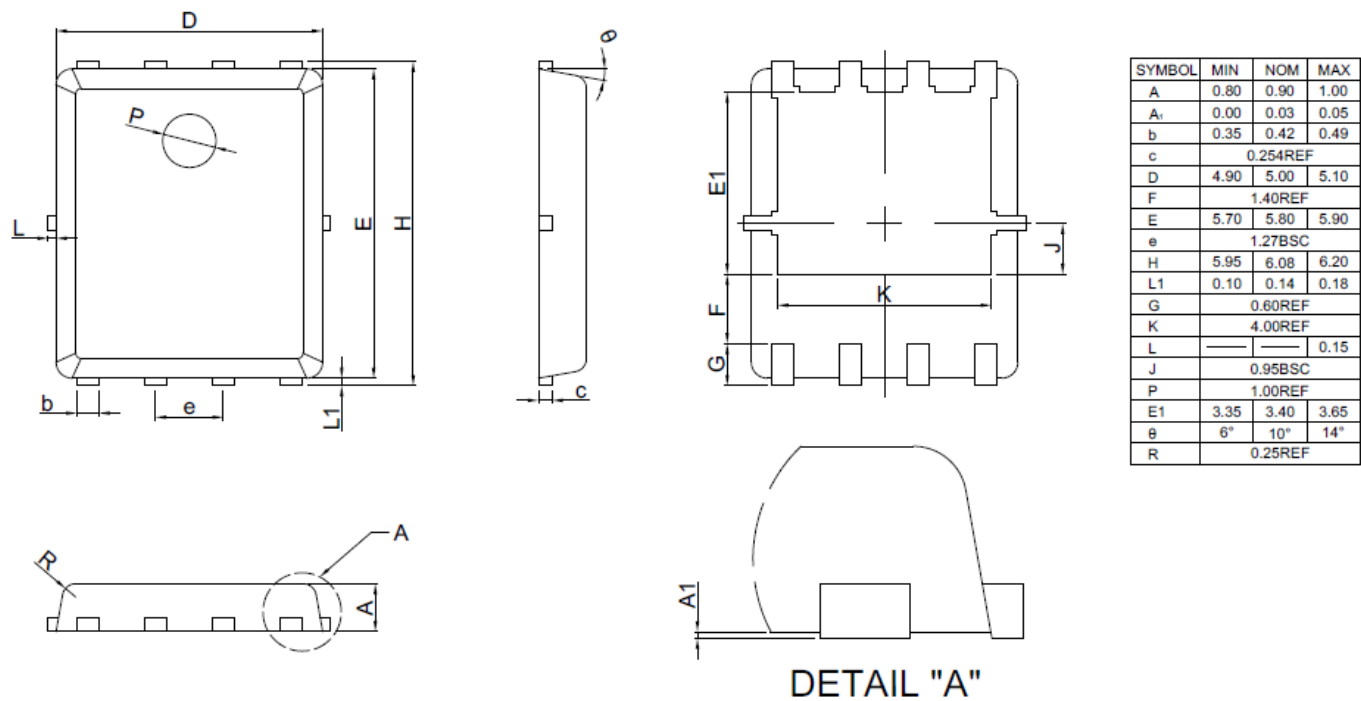
Switching Times Test Circuit for Inductive Load	Switching Times Waveform
	 V_{DS} V_{GS} 90% 10% $t_{D(on)}$ t_F $t_{D(off)}$ t_R

Table 9. Unclamped Inductive Load

Unclamped Inductive Load Test Circuit	Unclamped Inductive Waveform
	 $V_{(BR)DS}$ V_{DS} I_D

7. Package Outlines

Figure 1 Outline DFN5*6 Dimensions in mm



8. Appendix

CoolSemi Webpage: www.coolsemi.com.